

881F Series High-Current Fast Opening SMD Fuse



Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE
c FU °us	E71611	70 – 100A
€	NA	70 – 100A

Electrical Characteristics for Series

% of Ampere Rating	OpeningTime
100%	1 Hour, Min.
200%	60 Seconds, Max.

Applications

- Blade Servers
- Routers
- High-power Battery
 Systems

Electrical Specifications by Item

Power Factor Correction (PFC) in high wattage power supplies

 Power Distribution Units (PDUs)

Description

This high-current SMD fuse is a small, square, surface mount fuse that is designed as supplemental overcurrent protection for high-current circuits in various applications. This faster opening version enhances protection of the product from overload and short circuit current events in the application.

Features

- Available in 70A, 80A, and 100A ratings
- High interrupting rating -1500A @ 75Vdc
- With faster opening time response
- Surface mountable high current fuse

Lead-free, Halogen-free, and RoHS compliant

fuse design

UL Recognized to
 UL/CSA/NMX 248-1

Robust and solderless

RoHS 🗭 HF (C c 🖓 us

Benefits

- Single fuse solution for high current applications
- Suitable for a wide variety of voltage requirement and application
- Guaranteed protection against overload and short circuit current events
- Compatible with high volume assembly requirements
- Enhanced product reliability and performance

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (mOhms)	Nominal Voltage Drop * (mV)	Nominal Melting ** I²t (A²sec)	Agency Approvals c Sus
70	070.	75Vdc	1500A @75Vdc	0.82	89	1050	Х
80	080.			0.63	86	2000	Х
100	100.			0.52	96	4800	Х

* Nominal Voltage Drop measured at 100% rated Current. ** Nominal Melting I²t measured at 1500A.

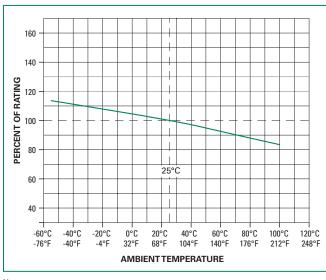
Thermal Characteristics

Ampere Rating I_n (A)	Typical Case Temperature Rise (°C) *			
	@ 50%l _n	@ 75%l _n	@ 100%I _n	
70	16	38	73	
80	25	58	88	
100	32	60	127	

* Typical values based on tests conducted with fuse mounted on FR-4 circuit board of 0.062" (1.6 mm) thickness with 6 oz. (210 µm) Cu.



Temperature Re-rating Curve



Note:

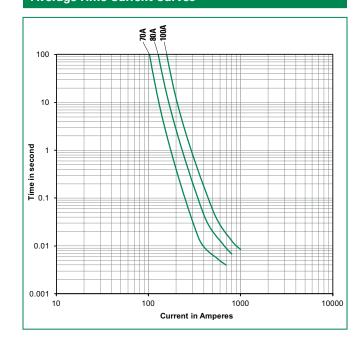
1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Example:

For continuous operation at 70°C, the fuse should be re-rated as follows: I = $(0.75)(0.90)I_{RAT} = (0.675)I_{RAT}$

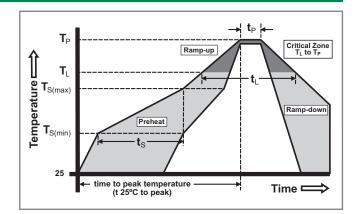
2. The temperature re-rating curve represents nominal conditions. For questions about the temperature re-rating curve, please consult Littlefuse technical support assistance.

Average Time Current Curves



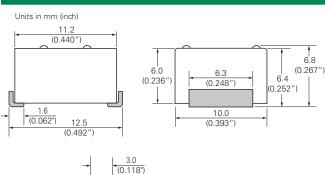
Soldering Parameters

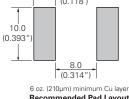
Reflow Condition		Pb – Free assembly	
Number o	f allowed reflow cycles	3	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 180 secs	
Average ra (T _L) to pea	amp up rate (LiquidusTemp k	5°C/second max.	
T _{S(max)} to T _L - Ramp-up Rate		5°C/second max.	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
nellow	-Temperature (t _L)	60 – 150 seconds	
PeakTemp	erature (T _P)	260+0/-5 °C	
Time with Temperatu	in 5°C of actual peak ıre (t _p)	20 – 40 seconds	
Ramp-down Rate		5°C/second max.	
Time 25°C	to peakTemperature (T _P)	8 minutes max.	
Do not exc	ceed	260°C	





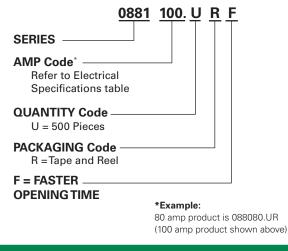






Recommended Pad Layout

Part Numbering System



Product Characteristics

Materials	Body: Thermoplastic, RTI 150°C Terminations: Tin-plated Copper		
Product Marking	Brand logo, Voltage Rating, 'F' (Faster Opening Time), and Ampere Rating		
Operating Temperature ^{1 2}	-55° to +100°C with proper derating		

Notes:

1. Based on loading at 75% of ampere rating when mounted using recommended pad layout. Usage outside of stated operating temperature range requires testing in application. Maintain case temperature below 150°C in application.

Thermal Shock	MIL-Std 202 Method 107 Test Condition B (-65°C to 125°C, 5 cycles).		
Moisture Resistance	MIL-Std 202 method 106 High Humidity (90-98%RH), Heat (65°C)		
Vibration	MIL-STD-202, Method 201 (10-55 Hz)		
Mechanical Shock	MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds)		
Resistance to Solder Heat	MIL-Std 202 Method 210 Test Condition B (10sec at 260°C)		
Solderability	MIL-STD-202 Method 208		
MSL Test	Level 1 J-STD-020		
Salt Fog	MIL-Std 202 Method 101 Test Condition B (5% NaCL solution, 48 hours exposure)		

Packaging				
Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	
24mm Tape and Reel	EIA-481 Rev. D (IEC 60286, part 3)	500	UR	

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